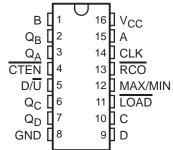
### CD54HC190, CD74HC190 CD54HC191, CD74HC191, CD54HCT191, CD74HCT191 SYNCHRONOUS UP/DOWN COUNTERS WITH DOWN/UP MODE CONTROL

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- 2-V to 6-V V<sub>CC</sub> Operation ('HC190, 191)
- 4.5-V to 5.5-V V<sub>CC</sub> Operation ('HCT191)
- Wide Operating Temperature Range of -55°C to 125°C
- Synchronous Counting and Asynchronous Loading
- Two Outputs for n-Bit Cascading
- Look-Ahead Carry for High-Speed Counting
- Balanced Propagation Delays and Transition Times
- Standard Outputs Drive Up To 15 LS-TTL Loads
- Significant Power Reduction Compared to LS-TTL Logic ICs

# CD54HC190, 191; CD54HCT191 . . . F PACKAGE CD74HC190 . . . E, NS, OR PW PACKAGE CD74HC191, CD74HCT191 . . . E OR M PACKAGE (TOP VIEW)



### description/ordering information

The CD54/74HC190 are asynchronously presettable BCD decade counters, whereas the CD54/74HC191 and CD54/74HCT191 are asynchronously presettable binary counters.

Presetting the counter to the number on preset data inputs (A–D) is accomplished by a low asynchronous parallel load ( $\overline{\text{LOAD}}$ ) input. Counting occurs when  $\overline{\text{LOAD}}$  is high, count enable ( $\overline{\text{CTEN}}$ ) is low, and the down/up ( $\overline{\text{D/U}}$ ) input is either high for down counting or low for up counting. The counter is decremented or incremented synchronously with the low-to-high transition of the clock.

### ORDERING INFORMATION

TA	PACK	AGE <sup>†</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING
			CD74HC190E	CD74HC190E
	PDIP – E	Tube of 25	CD74HC191E	CD74HC191E
			CD74HCT191E	CD74HCT191E
	SOIC - M	Tube of 40	CD74HC191M	
		Reel of 2500	CD74HC191M96	HC191M
		Reel of 250	CD74HC191MT	
		Tube of 40	CD74HCT191M	HCT191M
–55°C to 125°C	SOP - NS	Reel of 2000	CD74HC190NSR	HC190M
		Tube of 90	CD74HC190PW	
	TSSOP - PW	Reel of 2000	CD74HC190PWR	HJ190
		Reel of 250	CD74HC190PWT	
			CD54HC190F3A	CD54HC190F3A
	CDIP – F	Tube of 25	CD54HC191F3A	CD54HC191F3A
			CD54HCT191F3A	CD54HCT191F3A

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



### description/ordering information (continued)

When an overflow or underflow of the counter occurs, the MAX/MIN output, which is low during counting, goes high and remains high for one clock cycle. This output can be used for look-ahead carry in high-speed cascading (see Figure 1). The MAX/MIN output also initiates the ripple clock (RCO) output, which normally is high, goes low, and remains low for the low-level portion of the clock pulse. These counters can be cascaded using RCO (see Figure 2).

If a decade counter is preset to an illegal state or assumes an illegal state when power is applied, it returns to the normal sequence in one or two counts, as shown in the state diagrams (see Figure 3).

#### **FUNCTION TABLE**

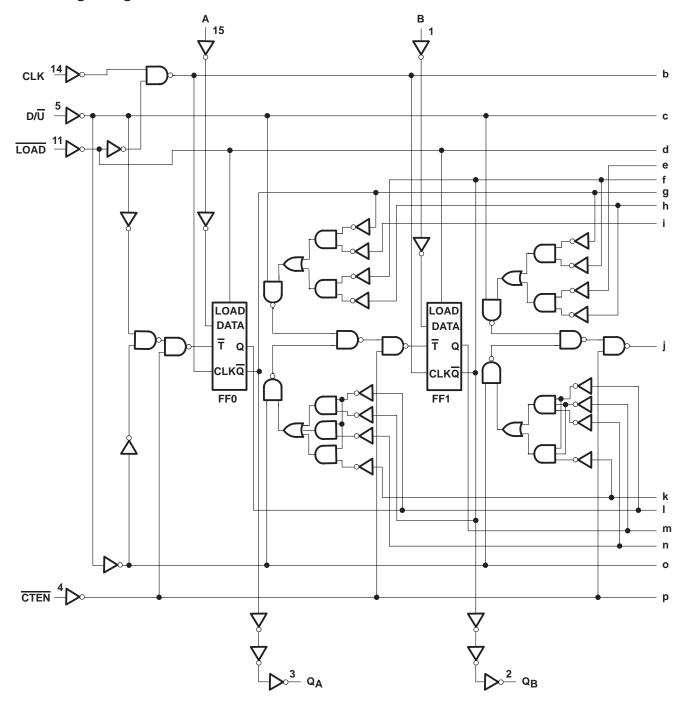
	INP	JTS		FUNCTION
LOAD	CTEN	D/ <del>U</del>	CLK	FUNCTION
Н	L	L		Count up
Н	L	Н		Count down
L	Х	Х	Х	Asynchronous preset
Н	Н	Х	Х	No change

 $\overline{D}/\overline{U}$  or  $\overline{CTEN}$  should be changed only when clock is high.

X = Don't care

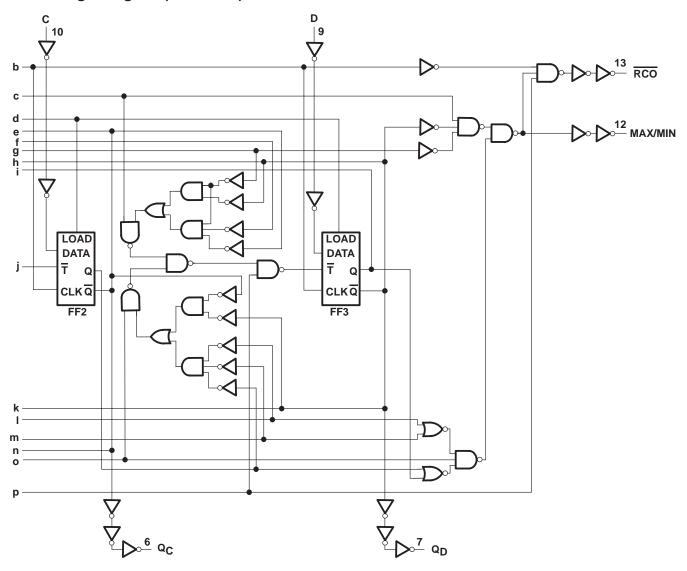


### 'HC190 logic diagram



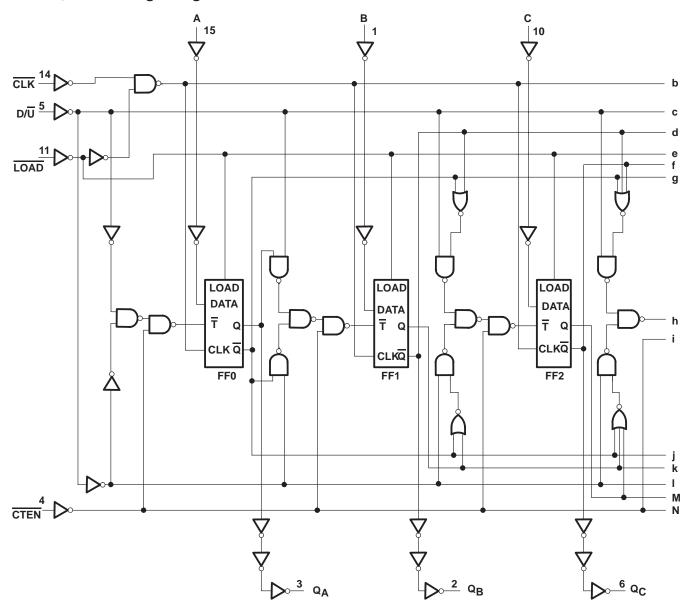


### 'HC190 logic diagram (continued)

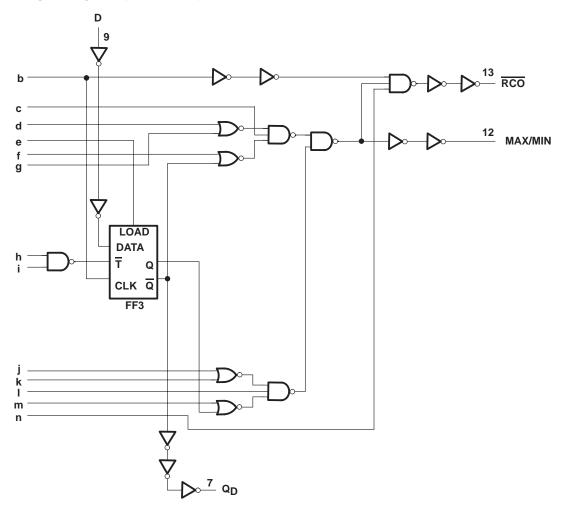




### 'HC191, 'HCT191 logic diagram

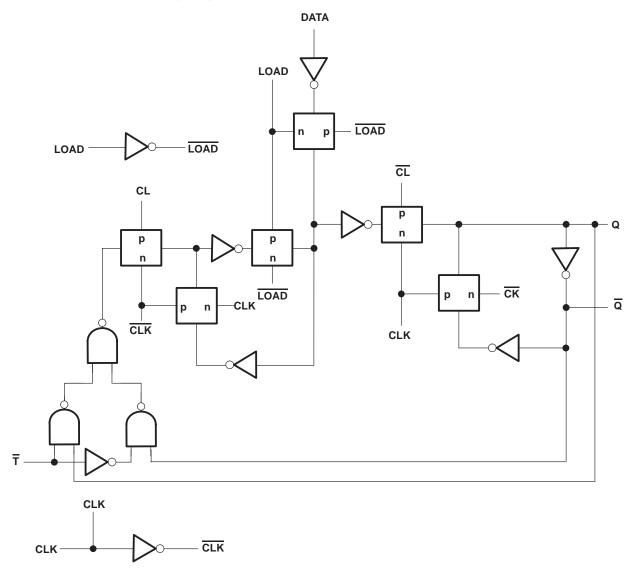


### 'HC191, 'HCT191 logic diagram (continued)





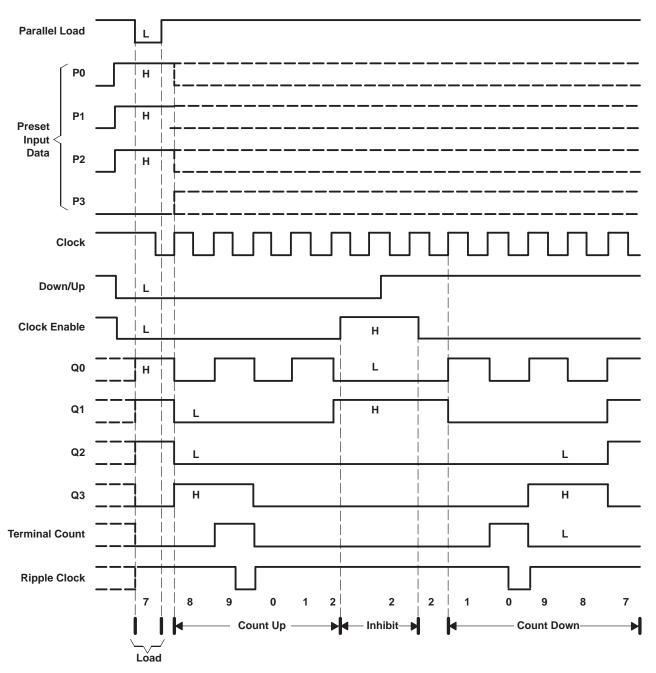
### 'HC190 and 'HC191/HCT191 flip-flop



### typical load, count, and inhibit sequence for 'HC190

The following sequence is illustrated below:

- 1. Load (preset) to BCD 7
- 2. Count up to 8, 9 (maximum), 0, 1, and 2
- 3. Inhibit
- 4. Count down to 1, 0 (minimum), 9, 8, and 7

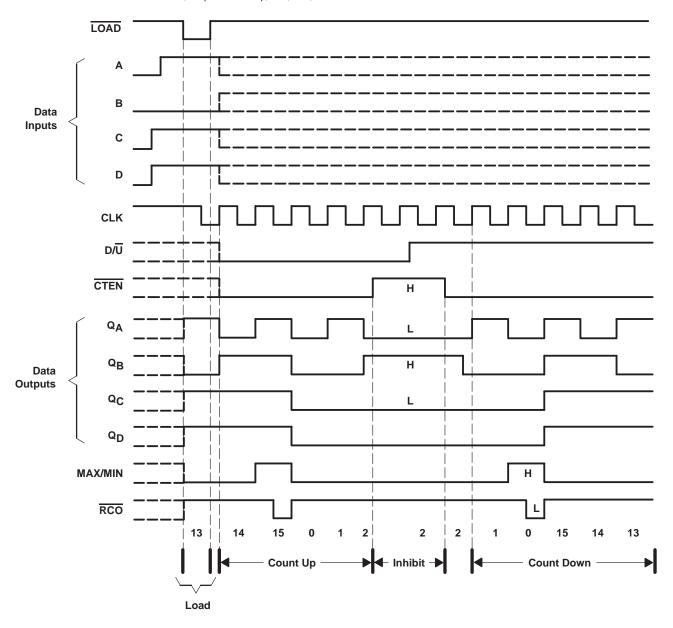




### typical load, count, and inhibit sequence for 'HC191 and 'HCT191

The following sequence is illustrated below:

- 1. Load (preset) to binary 13
- 2. Count up to 14, 15 (maximum), 0, 1, and 2
- 3. Inhibit
- 4. Count down to 1, 0 (minimum), 15, 14, and 13



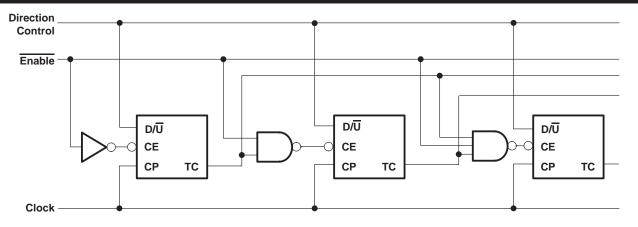


Figure 1. 'HC190 Synchronous n-Stage Counter With Parallel Gated Terminal Count

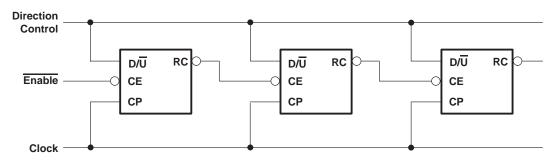


Figure 2. 'HC191, 'HCT191 Synchronous n-Stage Counter With Parallel Gated Terminal Count

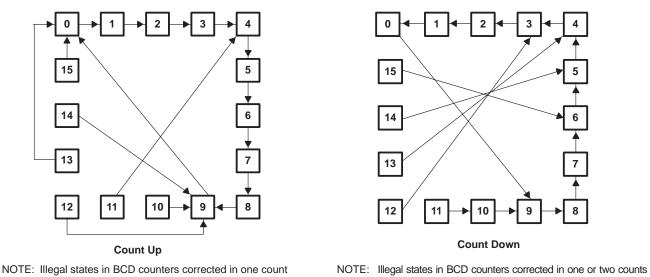


Figure 3. 'HC190 State Diagram



### CD54HC190, CD74HC190 CD54HC191, CD74HC191, CD54HCT191, CD74HCT191 SYNCHRONOUS UP/DOWN COUNTERS WITH DOWN/UP MODE CONTROL

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### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>		–0.5 V to 7 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see	e Note 1)	±20 mA
Output clamp current, IOK (VO < 0 or VO > VCC	c) (see Note 1)	±20 mA
Continuous output drain current per output, IO (	$V_O = 0$ to $V_{CC}$ )	±35 mA
Continuous output source or sink current per ou	utput, $I_O (V_O = 0 \text{ to } V_{CC})$	±25 mA
Continuous current through V <sub>CC</sub> or GND		±50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2):	E package	67°C/W
	M package	73°C/W
	NS package	64°C/W
	PW package	108°C/W
Storage temperature range, T <sub>stg</sub>		. –65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### recommended operating conditions for 'HC190 and 'HC191 (see Note 3)

			T <sub>A</sub> = 1	25°C	T <sub>A</sub> = -		T <sub>A</sub> = -		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
Vcc	Supply voltage		2	6	2	6	2	6	V
		V <sub>CC</sub> = 2 V	1.5		1.5		1.5		
$V_{IH}$	High-level input voltage	V <sub>CC</sub> = 4.5 V	3.15		3.15		3.15		V
		VCC = 6 V	4.2		4.2		4.2		
		V <sub>CC</sub> = 2 V		0.5		0.5		0.5	
$V_{IL}$	Low-level input voltage	V <sub>CC</sub> = 4.5 V		1.35		1.35		1.35	V
		VCC = 6 V		1.8		1.8		1.8	
٧ <sub>I</sub>	Input voltage		0	VCC	0	Vcc	0	Vcc	V
٧o	Output voltage		0	VCC	0	Vcc	0	Vcc	V
		V <sub>CC</sub> = 2 V		1000		1000		1000	
t <sub>t</sub>	t <sub>t</sub> Input transition (rise and fall) time	V <sub>CC</sub> = 4.5 V		500		500		500	ns
		VCC = 6 V		400		400		400	

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

### recommended operating conditions for 'HCT191 (see Note 4)

		T <sub>A</sub> = 2	25°C	T <sub>A</sub> = -		T <sub>A</sub> = -		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
VCC	Supply voltage	4.5	5.5	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2		2		2		V
VIL	Low-level input voltage		8.0		0.8		0.8	V
VI	Input voltage		VCC		VCC		VCC	V
VO	Output voltage		VCC		VCC		VCC	V
t <sub>t</sub>	Input transition (rise and fall) time		500	·	500		500	ns

NOTE 4: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

<sup>2.</sup> The package thermal impedance is calculated in accordance with JESD 51-7.

### CD54HC190, CD74HC190 CD54HC191, CD74HC191, CD54HCT191, CD74HCT191 SYNCHRONOUS UP/DOWN COUNTERS WITH DOWN/UP MODE CONTROL

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### 'HC190, 'HC191

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CO	NDITIONS	VCC	T <sub>A</sub> = 2	25°C	T <sub>A</sub> = -		T <sub>A</sub> = -		UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	
			2 V	1.9		1.9		1.9		
		$I_{OH} = -20  \mu A$	4.5 V	4.4		4.4		4.4		
VOН	VI = VIH or VIL		6 V	5.9		5.9		5.9		V
		$I_{OH} = -4 \text{ mA}$	4.5 V	3.98		3.7		3.84		
		$I_{OH} = -5.2 \text{ mA}$	6 V	5.48		5.2		5.34		
			2 V		0.1		0.1		0.1	
		$I_{OL} = 20 \mu\text{A}$	4.5 V		0.1		0.1		0.1	
V <sub>OL</sub>	$V_I = V_{IH}$ or $V_{IL}$		6 V		0.1		0.1		0.1	V
		I <sub>OL</sub> = 4 mA	4.5 V		0.26		0.4		0.33	
		I <sub>OL</sub> = 5.2 mA	6 V		0.26		0.4		0.33	
lį	$V_I = V_{CC}$ or 0		6 V		±0.1		±1		±1	μΑ
Icc	$V_I = V_{CC}$ or 0,	IO = 0	6 V		8		160		80	μΑ
C <sub>i</sub>					10		10		10	pF

### 'HCT191

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		Vcc	T <sub>A</sub> = 25°C			T <sub>A</sub> = -		T <sub>A</sub> = -		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	$I_{OH} = -20  \mu A$	45.77	4.4			4.4		4.4		
VOH	$V_I = V_{IH}$ or $V_{IL}$	$I_{OH} = -4 \text{ mA}$	4.5 V	3.98			3.7		3.84		٧
.,	Var. Var. Sa.Var.	$I_{OL} = 20 \mu A$	451/			0.1		0.1		0.1	
VOL	VI = VIH  or  VIL	I <sub>OL</sub> = 4 mA	4.5 V			0.26		0.4		0.33	٧
lį	$V_I = V_{CC}$ to GND		5.5 V			±0.1		±1		±1	μΑ
Icc	$V_I = V_{CC}$ or 0,	IO = 0	5.5 V			8		160		80	μА
ΔI <sub>CC</sub> †	One input at V <sub>CC</sub> – Other inputs at 0 or	2.1 V, V <sub>CC</sub>	4.5 V to 5.5 V		100	360		490		450	μΑ
Ci						10		10		10	pF

<sup>†</sup> Additional quiescent supply current per input pin, TTL inputs high, 1 unit load

### **HCT INPUT LOADING TABLE**

INPUTS	UNIT LOADS
A-D	0.4
CLK	1.5
LOAD	1.5
D/ <del>U</del>	1.2
CTEN	1.5

Unit load is  $\Delta I_{CC}$  limit specified in electrical characteristics table, (e.g., 360 μA max at 25°C).



## CD54HC190, CD74HC190 CD54HC191, CD74HC191, CD54HCT191, CD74HCT191 SYNCHRONOUS UP/DOWN COUNTERS WITH DOWN/UP MODE CONTROL SCHS275E - MARCH 2002 - REVISED OCTOBER 2003

### 'HC190, 'HC191 timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 4)

Clock   Clock frequency    Clock   Clock frequency    Clock				vcc	T <sub>A</sub> = 2	25°C	T <sub>A</sub> = -	-55°C 25°C	T <sub>A</sub> = -	-40°C 5°C	UNIT
Folicy   Clock frequency   Tolor   Clock frequency   Tolor   Clock   Tolor   Clock   Clock   Tolor   Clock   Clock   Tolor   Clock					MIN	MAX	MIN	MAX	MIN	MAX	
The color of the				2 V		6		4		5	
LOAD low	fclock	Clock frequency†		4.5 V		30		20		25	MHz
tw       Pulse duration       4.5 ∨ 16				6 V		35		23		29	
Etw       Pulse duration         CLK high or low       6 ∨ 14 20 17       ns         CLK high or low       CLK high or low       150 125       ns         Example of the CLK high or low       Data before \(\begin{center} \chi \chi \chi \chi \chi \chi \chi \chi				2 V	80		120		100		
tw         Pulse duration         2 ∨ 100			LOAD low	4.5 V	16		24		20		
CLK high or low		5.1.1.0		6 V	14		20		17		
The content of the following intent of the content of the conte	t <sub>W</sub>	Pulse duration		2 V	100		150		125		ns
Interval 1       Data before LOAD↑       2 V 60 90 75 90 75 90 135 13 13 13 15 13 13 15 13 13 15 13 13 15 15 13 13 15 15 13 13 15 15 13 15 15 13 13 15 15 13 13 15 15 13 13 15 15 13 13 15 15 13 13 15 15 13 15 15 15 13 15 15 15 15 15 15 15 15 15 15 15 15 15			CLK high or low	4.5 V	20		30		25		
tsu       Setup time       Data before LOAD↑       4.5 ∨ 12				6 V	17		26		21		
$t_{SU}  \text{Setup time}  \begin{array}{ c c c c c c }\hline & 6 \lor & 10 & 15 & 13 \\ \hline & & & & 2 \lor & 60 & 90 & 75 \\ \hline & & & & 4.5 \lor & 12 & 18 & 15 \\ \hline & & & & 10 & 15 & 13 \\ \hline & & & & 10 & 15 & 13 \\ \hline & & & & 2 \lor & 90 & 135 & 115 \\ \hline & & & & & 115 & 23 & 20 \\ \hline & & & & & 15 & 23 & 20 \\ \hline & & & & & & 2 \lor & 2 & 2 \\ \hline & & & & & & 2 \lor & 2 & 2 \\ \hline & & & & & & 2 \lor & 2 & 2 \\ \hline & & & & & & 2 \lor & 2 & 2 \\ \hline & & & & & & 2 \lor & 2 & 2 & 2 \\ \hline & & & & & & 2 \lor & 2 & 2 & 2 \\ \hline & & & & & & 2 \lor & 2 & 2 & 2 \\ \hline & & & & & & 2 \lor & 2 & 2 & 2 \\ \hline & & & & & & & & 2 \lor & 2 & 2 & 2 \\ \hline & & & & & & & & & & & & & & & & & &$				2 V	60		90		75		
tsu       Setup time       2 ∨ 60 90 75 90 75 90 90 75 13 13 15 13 13 15 115 13 13 15 115 15 13 15 15 15 15 15 15 15 15 15 15 15 15 15			Data before <del>LOAD</del> ↑	4.5 V	12		18		15		
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$				6 V	10		15		13		
Box   Figure   Figu				2 V	60		90		75		
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	t <sub>su</sub>	Setup time	CTEN before CLK↑	4.5 V	12		18		15		ns
D/Ū before CLK↑		•		6 V	10		15		13		
Data before LOAD↑   2V   2   2   2   2   2   2   4.5 V   2   2   2   2   2   2   2   2   2				2 V	90		135		115		
$t_{h}  \text{Hold time}  \begin{array}{ c c c c c c c c }\hline & 2V & 2 & 2 & 2 & 2 \\ \hline & 4.5 \ V & 2 & 2 & 2 & 2 \\ \hline & 6V & 2 & 2 & 2 & 2 \\ \hline & 2V & 2 & 2 & 2 & 2 \\ \hline & 2V & 2 & 2 & 2 & 2 \\ \hline & 4.5 \ V & 2 & 2 & 2 & 2 \\ \hline & 6V & 2 & 2 & 2 & 2 \\ \hline & 6V & 2 & 2 & 2 & 2 \\ \hline & 2V & 0 & 0 & 0 & 0 \\ \hline & 6V & 2 & 0 & 0 & 0 \\ \hline & 4.5 \ V & 0 & 0 & 0 & 0 \\ \hline & 4.5 \ V & 0 & 0 & 0 & 0 \\ \hline & 4.5 \ V & 0 & 0 & 0 & 0 \\ \hline & 100 \ \hline$			D/ <del>U</del> before CLK↑	4.5 V	18		27		23		
$t_{h}  \text{Hold time}  \begin{array}{ c c c c c c c c }\hline \text{Data before $\overline{LOAD}$} & 4.5\text{V} & 2 & 2 & 2 & 2 \\\hline & 6\text{V} & 2 & 2 & 2 & 2 & 2 \\\hline & 2\text{V} & 2 & 2 & 2 & 2 & 2 \\\hline & 2\text{V} & 2 & 2 & 2 & 2 & 2 \\\hline & 6\text{V} & 2 & 2 & 2 & 2 & 2 \\\hline & 6\text{V} & 2 & 2 & 2 & 2 & 2 \\\hline & 2\text{V} & 0 & 0 & 0 & 0 & 0 \\\hline & 2\text{V} & 0 & 0 & 0 & 0 & 0 \\\hline & 4.5\text{V} & 0 & 0 & 0 & 0 & 0 \\\hline & 4.5\text{V} & 0 & 0 & 0 & 0 & 0 \\\hline & t_{rec} & \text{Recovery time} & \hline & \overline{LOAD} \text{ inactive before CLK} & 4.5\text{V} & 12 & 18 & 15 & ns \\\hline \end{array}$				6 V	15		23		20		
$t_{h}  \text{Hold time}  \begin{array}{ c c c c c c }\hline 6 \ V & 2 & 2 & 2 \\ \hline 2 \ V & 2 & 2 & 2 \\ \hline CTEN \text{ before CLK} \uparrow & 4.5 \ V & 2 & 2 & 2 \\ \hline 6 \ V & 2 & 2 & 2 & 2 \\ \hline 6 \ V & 2 & 2 & 2 & 2 \\ \hline 2 \ V & 0 & 0 & 0 & 0 \\ \hline 4.5 \ V & 0 & 0 & 0 & 0 \\ \hline 6 \ V & 0 & 0 & 0 & 0 \\ \hline \hline t_{rec}  \text{Recovery time} & \hline LOAD \text{ inactive before CLK} \uparrow & 4.5 \ V & 12 & 18 & 15 & ns \\ \hline \end{array}$				2 V	2		2		2		
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$			Data before LOAD↑	4.5 V	2		2		2		
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$				6 V	2		2		2		
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$				2 V	2		2		2		
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	th	Hold time	CTEN before CLK↑	4.5 V	2		2		2		ns
D/U before CLK↑     4.5 V     0     0     0       6 V     0     0     0       1 trec     Recovery time     LOAD inactive before CLK↑     4.5 V     12     18     15     ns				6 V	2		2		2		
6 V     0     0       2 V     60     90     75       LOAD inactive before CLK↑     4.5 V     12     18     15     ns				2 V	0		0		0		
6 V     0     0       2 V     60     90     75       LOAD inactive before CLK↑     4.5 V     12     18     15     ns			D/ <del>U</del> before CLK↑	4.5 V	0		0		0		
trec Recovery time LOAD inactive before CLK↑ 4.5 V 12 18 15 ns					0		0		0		
$t_{\text{rec}}$ Recovery time $\overline{\text{LOAD}}$ inactive before CLK $\uparrow$ 4.5 V 12 18 15 ns				2 V	60		90		75		
	trec	Recovery time	LOAD inactive before CLK↑								ns
1	100	,		6 V	10		15		13		

<sup>†</sup> Applies to noncascaded operation only. With cascaded counters, clock-to-terminal count propagation delays, CTEN-to-clock setup times, and CTEN-to-clock hold times determine maximum clock frequency. For example, with these HC devices:

$$f_{max}(CLK) = \frac{1}{CLK - to - MAX/MIN \ propagation \ delay + \overline{CTEN} - to - CLK \ setup \ time + \overline{CTEN} - to - CLK \ hold \ time} = \frac{1}{42 + 12 + 2} \approx 18 \ MHz$$



'HC190, 'HC191

### switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 4)

PARAMETER	FROM	TO	LOAD	Vcc	T,	գ = 25°C	;	T <sub>A</sub> = -	.55°C 25°C	T <sub>A</sub> = -	-40°C 5°C	UNIT
	(INPUT)	(OUTPUT)	CAPACITANCE		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
				2 V	6			4		5		
f <sub>max</sub>				4.5 V	30			20		25		MHz
				6 V	35			23		29		
				2 V			195		295		245	
	LOAD	Q	C <sub>L</sub> = 50 pF	4.5 V			39		59		49	
	LOAD	Q		6 V			33		50		42	
			C <sub>L</sub> = 15 pF	5 V		16						
				2 V			175		265		220	
	A, B, C,	Q	$C_L = 50 pF$	4.5 V			35		53		44	
	or D	ų ų		6 V			30		45		37	
			$C_L = 15 pF$	5 V		14						
				2 V			170		255		215	
	CLK	Q	$C_{L} = 50 \text{ pF}$	4.5 V			34		51		43	
	OLIK			6 V			29		43		37	
			C <sub>L</sub> = 15 pF	5 V		14						
				2 V			125		190		155	
	CLK	RCO	C <sub>L</sub> = 50 pF	4.5 V			25		38 31			
	OLIK	1100		6 V			21		32		26	
<sup>t</sup> pd			C <sub>L</sub> = 15 pF	5 V		10						ns
φα				2 V			210		315		265	
	CLK	MAX/MIN	C <sub>L</sub> = 50 pF	4.5 V			42		63		53	
				6 V			36		54		45	
			C <sub>L</sub> = 15 pF	5 V		18						
				2 V			150		225		190	
	D/ <del>U</del>	RCO	C <sub>L</sub> = 50 pF	4.5 V			30		45		38	
				6 V			26		38		33	
			C <sub>L</sub> = 15 pF	5 V		12						
			_	2 V			165		250		205	
	D/ <del>U</del>	MAX/MIN	C <sub>L</sub> = 50 pF	4.5 V			33		50		41	
			0 15 5	6 V			28		43		35	
			C <sub>L</sub> = 15 pF	5 V		13	405		400		455	
				2 V			125		190		155	
	CTEN	RCO	C <sub>L</sub> = 50 pF	4.5 V			25		38		31	
			C: 45 = 5	6 V		40	21		32		26	
			C <sub>L</sub> = 15 pF	5 V		10	7.		440		25	
		Λ	0. 50.55	2 V			75		110		95	
t <sub>t</sub>		Any	C <sub>L</sub> = 50 pF	4.5 V			15		22		19	ns
				6 V			13		19		16	



### 'HCT191

### timing requirements over recommended operating free-air temperature range $V_{CC}$ = 4.5 V (unless otherwise noted) (see Figure 5)

			T <sub>A</sub> = 2	25°C	T <sub>A</sub> = -		T <sub>A</sub> = -		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
fclock	Clock frequency			30		20		25	MHz
4	Pulse duration	LOAD low	16		24		20		20
t <sub>W</sub>	Pulse duration	CLK high or low	20		30		25		ns
		Data before LOAD↑	12		18		15		
t <sub>su</sub>	Setup time	CTEN before CLK↑	12		18		15		ns
		D/U before CLK↑	18		27		23		
		Data before LOAD↑	2		2		2		
th	Hold time	CTEN before CLK↑	2		2		2		ns
		D/U before CLK↑	0		0		0		
t <sub>rec</sub>	Recovery time	LOAD inactive before CLK↑	12		18		15	·	ns

### 'HCT191

## switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 5)

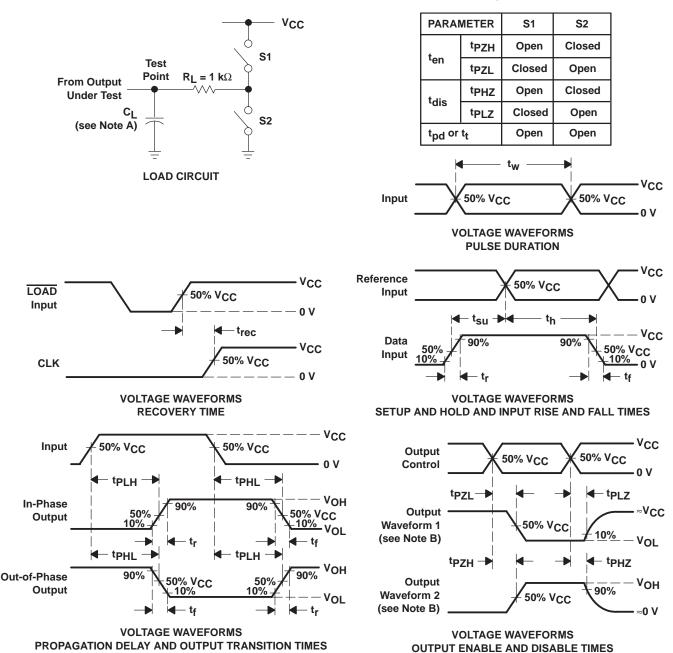
PARAMETER	FROM	TO	LOAD	Vcc	Т,	λ = 25°C	;	T <sub>A</sub> = -		T <sub>A</sub> = -		UNIT
	(INPUT)	(OUTPUT)	CAPACITANCE		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f <sub>max</sub>				4.5 V	30			20		25		MHz
	LOAD		$C_{L} = 50 \text{ pF}$	4.5 V			40		60		50	
	LOAD	Q	C <sub>L</sub> = 15 pF	5 V		17						
	A, B, C,		$C_L = 50 pF$	4.5 V			38		57		48	
	or D	Q	$C_L = 15 pF$	5 V		16						
	CLK	<del></del>	C <sub>L</sub> = 50 pF	4.5 V			35		53		44	
	CLK	RCO	C <sub>L</sub> = 15 pF	5 V		14						
	CLIK		C <sub>L</sub> = 50 pF	4.5 V			27		41		34	
	CLK	Q	C <sub>L</sub> = 15 pF	5 V		11						
<sup>t</sup> pd	CLIK	BAAV/BAINI	$C_{L} = 50 \text{ pF}$	4.5 V			42		63		53	ns
	CLK	MAX/MIN	C <sub>L</sub> = 15 pF	5 V		18						
	D/II	RCO	C <sub>L</sub> = 50 pF	4.5 V			30		45		38	
	D/Ū	RCO	C <sub>L</sub> = 15 pF	5 V		12						
		NA A V/NAINI	C <sub>L</sub> = 50 pF	4.5 V			38		57		48	
	D/Ū	MAX/MIN	C <sub>L</sub> = 15 pF	5 V		16						
	CTEN	<del></del>	C <sub>L</sub> = 50 pF	4.5 V			27		41		34	
	CIEN	RCO	C <sub>L</sub> = 15 pF	5 V		11						
t <sub>t</sub>		Any	C <sub>L</sub> = 50 pF	4.5 V			15		22		19	ns

# CD54HC190, CD74HC190 CD54HC191, CD74HC191, CD54HCT191, CD74HCT191 SYNCHRONOUS UP/DOWN COUNTERS WITH DOWN/UP MODE CONTROL SCHS275E - MARCH 2002 - REVISED OCTOBER 2003

### operating characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$

PARAMETER				
		'HC190	59 55	
С	Power dissipation capacitance	'HC191	55	pF
		'HCT191	68	

### PARAMETER MEASUREMENT INFORMATION - 'HC190, 'HC191



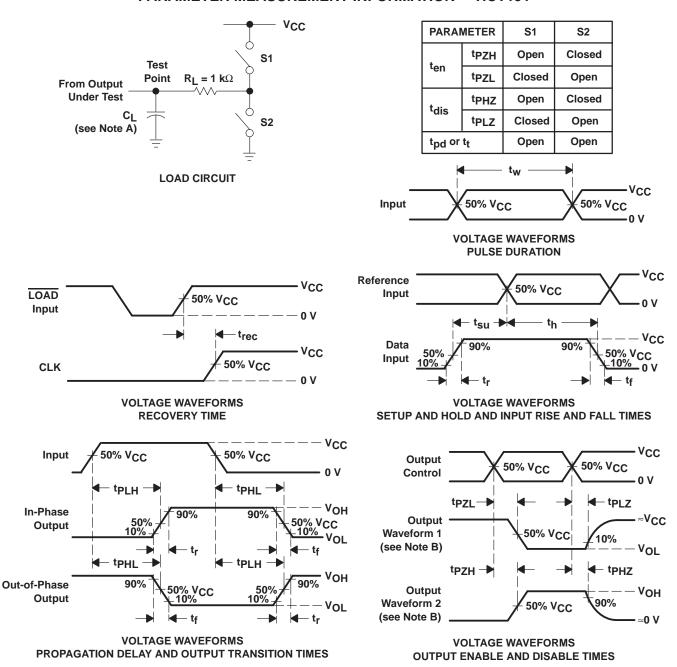
NOTES: A. C<sub>I</sub> includes probe and test-fixture capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz, Z<sub>O</sub> = 50  $\Omega$ , t<sub>f</sub> = 6 ns.
- D. For clock inputs, f<sub>max</sub> is measured with the input duty cycle at 50%.
- E. The outputs are measured one at a time with one input transition per measurement.
- F. tpLz and tpHz are the same as tdis.
- G. tpZL and tpZH are the same as ten.
- H. tpl H and tpHI are the same as tpd.

Figure 4. Load Circuit and Voltage Waveforms



### PARAMETER MEASUREMENT INFORMATION - 'HCT191



- NOTES: A. C<sub>I</sub> includes probe and test-fixture capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \Omega$ ,  $t_f = 6 \text{ ns}$ ,  $t_f = 6 \text{ ns}$ .
  - D. For clock inputs,  $f_{\text{max}}$  is measured with the input duty cycle at 50%.
  - E. The outputs are measured one at a time with one input transition per measurement.
  - F. tpLz and tpHz are the same as tdis.
  - G. tpzL and tpzH are the same as ten.
  - H. tpLH and tpHL are the same as tpd.

Figure 5. Load Circuit and Voltage Waveforms







24-Aug-2014

### **PACKAGING INFORMATION**

Orderable Device	Status	Package Type	_	Pins	_		Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
5962-8867101EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8867101EA CD54HCT191F3A	Samples
5962-8994601EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8994601EA CD54HC190F3A	Samples
CD54HC190F3A	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8994601EA CD54HC190F3A	Samples
CD54HC191F3A	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8689101EA CD54HC191F3A	Samples
CD54HCT191F3A	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8867101EA CD54HCT191F3A	Samples
CD74HC190E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD74HC190E	Samples
CD74HC190EE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD74HC190E	Samples
CD74HC190NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC190M	Samples
CD74HC190PW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HJ190	Samples
CD74HC190PWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HJ190	Samples
CD74HC191E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD74HC191E	Samples
CD74HC191EE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD74HC191E	Samples
CD74HC191M	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC191M	Samples
CD74HC191M96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC191M	Samples
CD74HC191M96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC191M	Samples
CD74HC191MG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC191M	Samples
CD74HC191MT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC191M	Samples



### PACKAGE OPTION ADDENDUM

24-Aug-2014

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
CD74HCT191E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD74HCT191E	Samples
CD74HCT191M	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT191M	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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24-Aug-2014

### OTHER QUALIFIED VERSIONS OF CD54HC190, CD54HC191, CD54HC191, CD74HC190, CD74HC191, CD74HC191:

- Catalog: CD74HC190, CD74HC191, CD74HCT191
- Military: CD54HC190, CD54HC191, CD54HCT191

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

### PACKAGE MATERIALS INFORMATION

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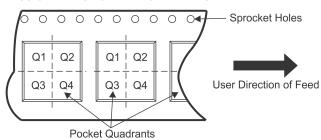
### TAPE AND REEL INFORMATION





Α0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

All ullicinions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74HC190NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
CD74HC190PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD74HC191M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

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### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74HC190NSR	SO	NS	16	2000	367.0	367.0	38.0
CD74HC190PWR	TSSOP	PW	16	2000	367.0	367.0	35.0
CD74HC191M96	SOIC	D	16	2500	333.2	345.9	28.6

### D (R-PDS0-G16)

### PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



### D (R-PDSO-G16)

### PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



### **MECHANICAL DATA**

### NS (R-PDSO-G\*\*)

### 14-PINS SHOWN

### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



### 14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

PW (R-PDSO-G16)

### PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



### PW (R-PDSO-G16)

### PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



### N (R-PDIP-T\*\*)

### PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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